Surface Mount Schottky Power Rectifier

SMA Power Surface Mount Package

This device employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State of the art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity diodes in surface mount applications where compact size and weight are critical to the system.

Features

- Small Compact Surface Mountable Package with J-Bent Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Very Low Forward Voltage Drop
- Guard-ring for Stress Protection
- NRVBA Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable*
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 70 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped in 12 mm tape, 5000 units per 13 inch reel
- Polarity: Cathode Lead Indicated by Polarity Band
- ESD Ratings:
 - Machine Model = C
 - Human Body Model = 3B



ON Semiconductor®

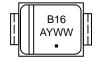
www.onsemi.com

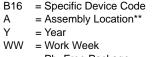
SCHOTTKY BARRIER RECTIFIER 1.0 AMPERES 60 VOLTS



SMA CASE 403D

MARKING DIAGRAM





= Pb–Free Package

(Note: Microdot may be in either location)

**The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRA160T3G	SMA (Pb–Free)	5,000 / Tape & Reel
NRVBA160T3G*	SMA (Pb–Free)	5,000 / Tape & Reel
NRVBA160T3G-VF01	SMA (Pb–Free)	5,000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	60	V
Average Rectified Forward Current (At Rated V _R , $T_C = 105^{\circ}C$)	Io	1.0	A
Average Rectified Forward Current (At Rated V_R , $T_C = 70^{\circ}C$)	lo	2.1	A
Non–Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	60	A
Storage/Operating Case Temperature	T _{stg} , T _C	-55 to +150	°C
Operating Junction Temperature (Note 1)	TJ	-55 to +150	°C
Voltage Rate of Change (Rated V_R , $T_J = 25^{\circ}C$)	dv/dt	10,000	V/µs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. The heat generated must be less than the thermal conductivity from Junction–to–Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

THERMAL CHARACTERISTICS

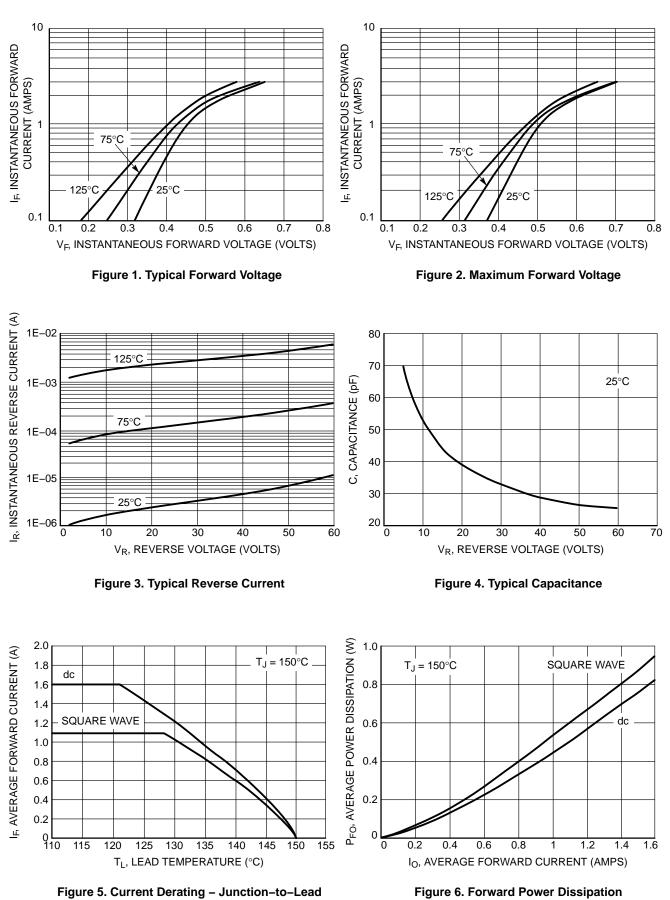
Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 2)	R _{θJL}	35	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	R _{θJA}	86	

2. Mounted on 2" Square PC Board with 1" Square Total Pad Size, PC Board FR4.

ELECTRICAL CHARACTERISTICS

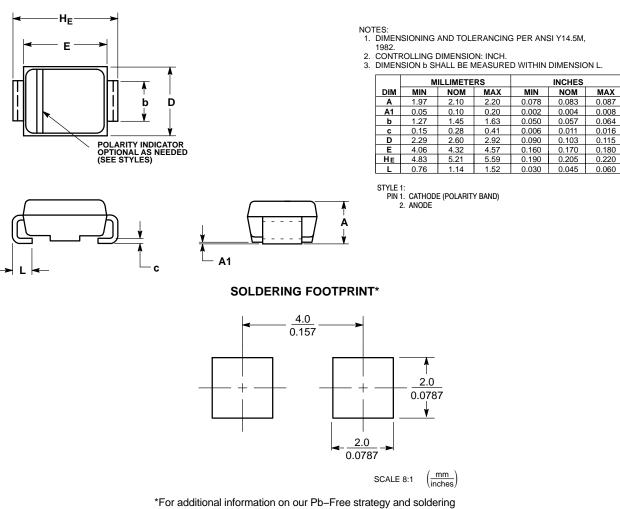
Characteristic	Symbol	Value		Unit
Maximum Instantaneous Forward Voltage (Note 3)	V _F	T _J = 25°C	T _J = 125°C	V
(I _F = 1.0 A)		0.510	0.475	
Maximum Instantaneous Reverse Current	I _R	T _J = 25°C	T _J = 125°C	mA
(V _R = 60 V)		0.2	20	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Pulse Test: Pulse Width \leq 250 µs, Duty Cycle \leq 2.0%.



PACKAGE DIMENSIONS

SMA CASE 403D ISSUE H



For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdt/Patent_Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor information provided by ON Semiconductor information provided by ON Semiconductor information provided by ON Semiconductor and the applications and safety requirements or standards, regardless of any support or applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights or the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor handles, and expenses, and expenses, and expenses, and expenses, and expenses, and expenses, and liamed for unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semico

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81–3–5817–1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative